

SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS118 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

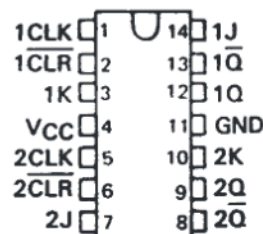
description

The '73, and 'H73, contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '73, and 'H73, are positive pulse-triggered flip-flops. J-K input is loaded into the master while the clock is high and transferred to the slave on the high-to-low transition. For these devices the J and K inputs must be stable while the clock is high.

The 'LS73A contains two independent negative-edge-triggered flip-flops. The J and K inputs must be stable one setup time prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Q output low and the $\bar{Q}$ output high.

The SN5473, SN54H73, and the SN54LS73A are characterized for operation over the full military temperature range of -55°C to 125°C . The SN7473, and the SN74LS73A are characterized for operation from 0°C to 70°C .

SN5473, SN54LS73A . . . J OR W PACKAGE
SN7473 . . . N PACKAGE
SN74LS73A . . . D OR N PACKAGE
(TOP VIEW)



'73
FUNCTION TABLE

INPUTS				OUTPUTS	
CLR	CLK	J	K	Q	$\bar{Q}$
L	X	X	X	L	H
H		L	L	Q_0	$\bar{Q}_0$
H		H	L	H	L
H		L	H	L	H
H		H	H	TOGGLE	TOGGLE

'LS73A
FUNCTION TABLE

INPUTS				OUTPUTS	
CLR	CLK	J	K	Q	$\bar{Q}$
L	X	X	X	L	H
H		L	L	Q_0	$\bar{Q}_0$
H		H	L	H	L
H		L	H	L	H
H		H	H	TOGGLE	TOGGLE
H	H	X	X	Q_0	$\bar{Q}_0$

FOR CHIP CARRIER INFORMATION,
CONTACT THE FACTORY

SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

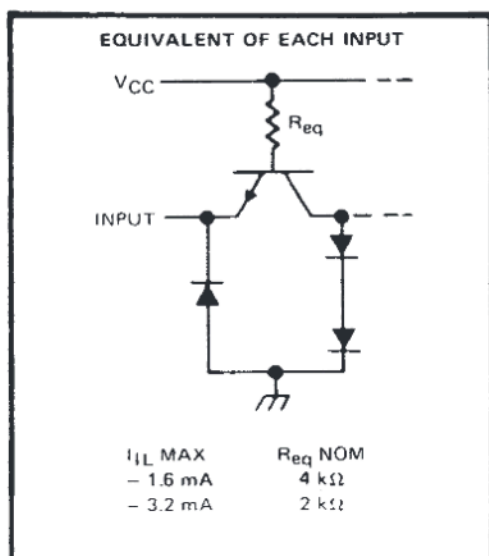
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logic symbols†

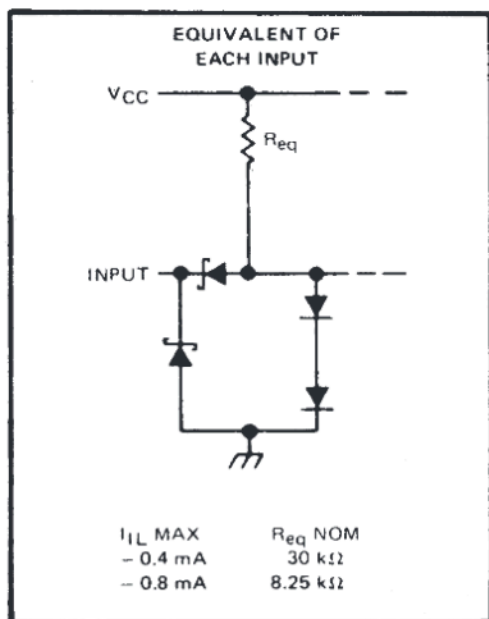
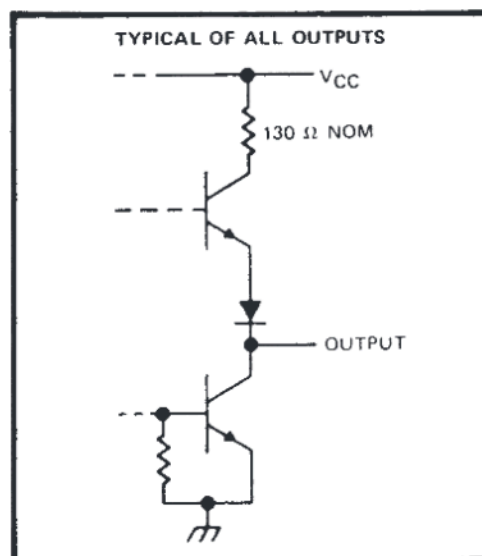


†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

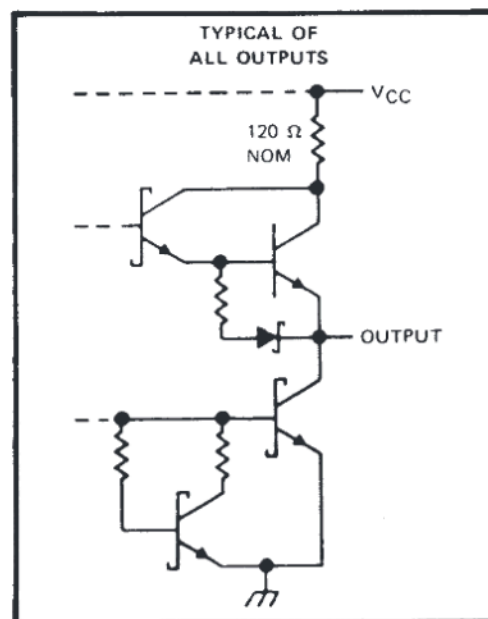
schematics of inputs and outputs



'73



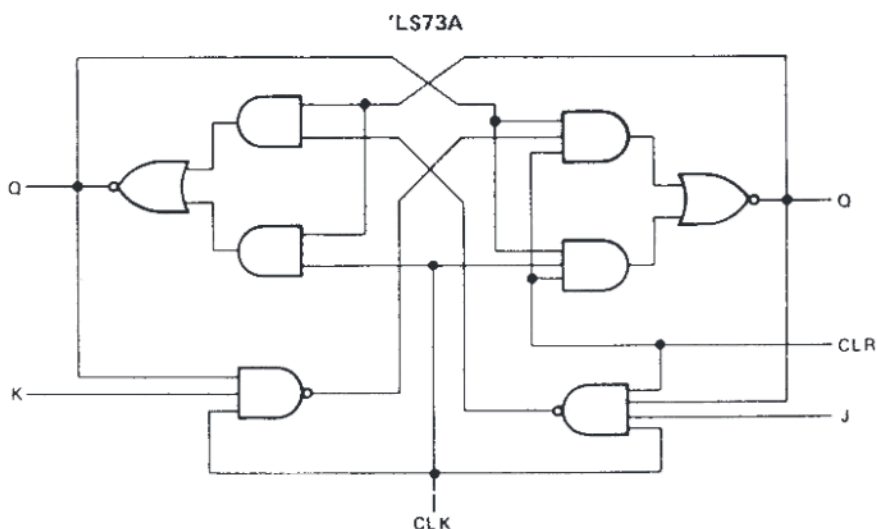
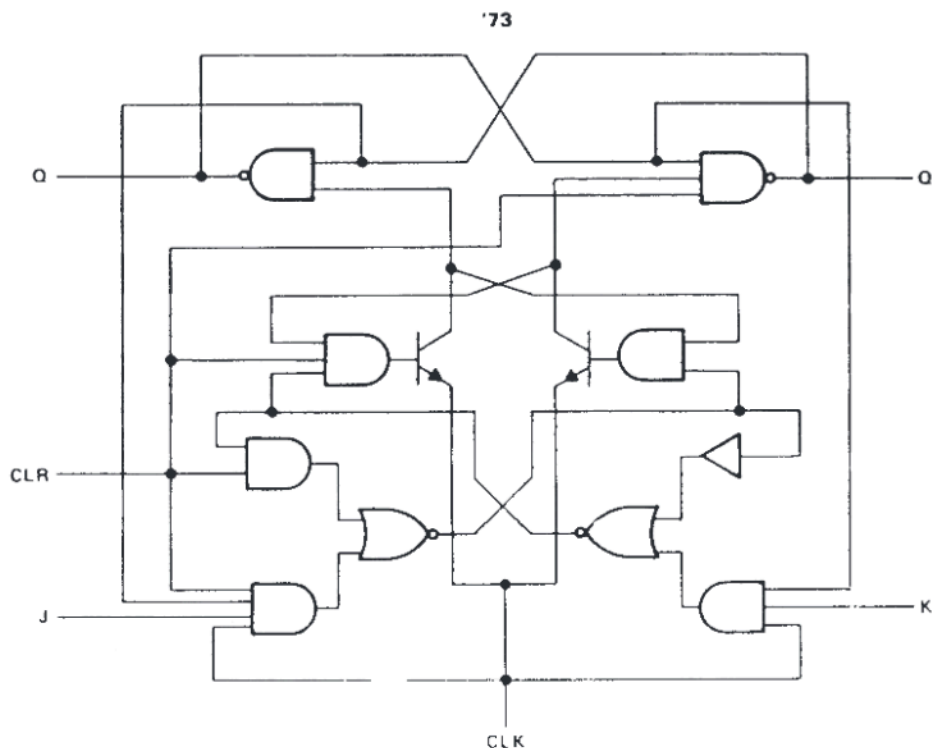
'LS73



SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

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logic diagrams (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (See Note 1)	7 V
Input voltage: '73	5.5 V
'LS73A	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

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recommended operating conditions

		SN5473			SN7473			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			-0.4			-0.4	mA
I_{OL}	Low-level output current			16			16	mA
t_w	Pulse duration	CLK high	20		20			ns
		CLK low	47		47			
		$\overline{CLR}$ low	25		25			
t_{su}	Input setup time before CLK $\uparrow$	0			0			ns
t_h	Input hold time data after CLK $\downarrow$	0			0			ns
T_A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN5473			SN7473			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}		$V_{CC} = \text{MIN}, I_I = -12 \text{ mA}$				-1.5			-1.5	V
V_{OH}		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OH} = -0.4 \text{ mA}$		2.4	3.4		2.4	3.4		V
V_{OL}		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 16 \text{ mA}$			0.2	0.4		0.2	0.4	V
I_I		$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$				1			1	mA
I_{IH}	J or K	$V_{CC} = \text{MAX}, V_I = 2.4 \text{ V}$				40			40	μA
	$\overline{CLR}$ or CLK					80			80	
I_{IL}	J or K	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$				-1.6			-1.6	mA
	$\overline{CLR}$					-3.2			-3.2	
	CLK					-3.2			-3.2	
$I_{OS}§$		$V_{CC} = \text{MAX}$		-20		-57	-18		-57	mA
$I_{CC}¶$		$V_{CC} = \text{MAX},$ See Note 2			10	20		10	20	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time.

¶ Average per flip-flop.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and $\overline{Q}$ outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ (see note 3)

PARAMETER#	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}				15	20		MHz
t_{PLH}	$\overline{CLR}$	$\overline{Q}$	$R_L = 400 \Omega, C_L = 15 \text{ pF}$		16	25	ns
t_{PHL}		Q			25	40	ns
t_{PLH}	CLK	Q or $\overline{Q}$			16	25	ns
t_{PHL}					25	40	ns

f_{max} = maximum clock frequency; t_{PLH} = propagation delay time, low-to-high-level output; t_{PHL} = propagation delay time, high-to-low-level output.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

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recommended operating conditions

		SN54LS73A			SN74LS73A			UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX			
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V		
V _{IH}	High-level input voltage	2			2			V		
V _{IL}	Low-level input voltage			0.7			0.8	V		
I _{OH}	High-level output current			− 0.4			− 0.4	mA		
I _{OL}	Low-level output current			4			8	mA		
f _{clock}	Clock frequency	0		30	0		30	MHz		
t _w	Pulse duration	CLK high			20			ns		
		CLR low			25					
t _{su}	Set up time-before CLK ↓	data high or low			20			ns		
		CLR inactive			20					
t _h	Hold time-data after CLK ↓	0			0			ns		
T _A	Operating free-air temperature	− 55			125			0	70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS73A			SN74LS73A			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}		V _{CC} = MIN, I _I = – 18 mA				– 1.5			– 1.5	V
V _{OH}		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX, I _{OH} = – 0.4 mA		2.5	3.4		2.7	3.4		V
V _{OL}		V _{CC} = MIN, V _{IL} = MAX, V _{IH} = 2 V, I _{OL} = 4 mA			0.25	0.4		0.25	0.4	V
		V _{CC} = MIN, V _{IL} = MAX, V _{IH} = 2 V, I _{OL} = 8 mA						0.35	0.5	
I _I	J or K	V _{CC} = MAX, V _I = 7 V				0.1			0.1	mA
	CLR					0.3			0.3	
	CLK					0.4			0.4	
I _{IH}	J or K	V _{CC} = MAX, V _I = 2.7 V				20			20	μA
	CLR					60			60	
	CLK					80			80	
I _{IL}	J or K	V _{CC} = MAX, V _I = 0.4 V				– 0.4			– 0.4	mA
	CLR or CLK					– 0.8			– 0.8	
I _{OS} §		V _{CC} = MAX, See Note 4		– 20		– 100	– 20		– 100	mA
I _{CC} (Total)		V _{CC} = MAX, See Note 2			4	6		4	6	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and $\bar{Q}$ outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}			R _L = 2 kΩ, C _L = 15 pF	30	45		MHz
t _{PLH}	CLR or CLK	Q or Q̄			15	20	ns
t _{PHL}					15	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9675101QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101VCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101VCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101VDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101VDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN7473N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7473N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7473N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7473N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS73AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS73AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS73ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS73ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SNJ54LS73AFD	OBSOLETE	LCCC	FK	20		TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AFD	OBSOLETE	LCCC	FK	20		TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

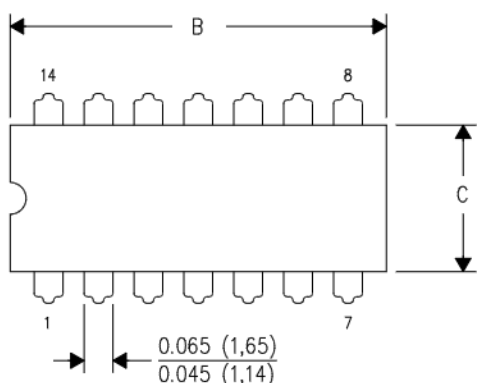
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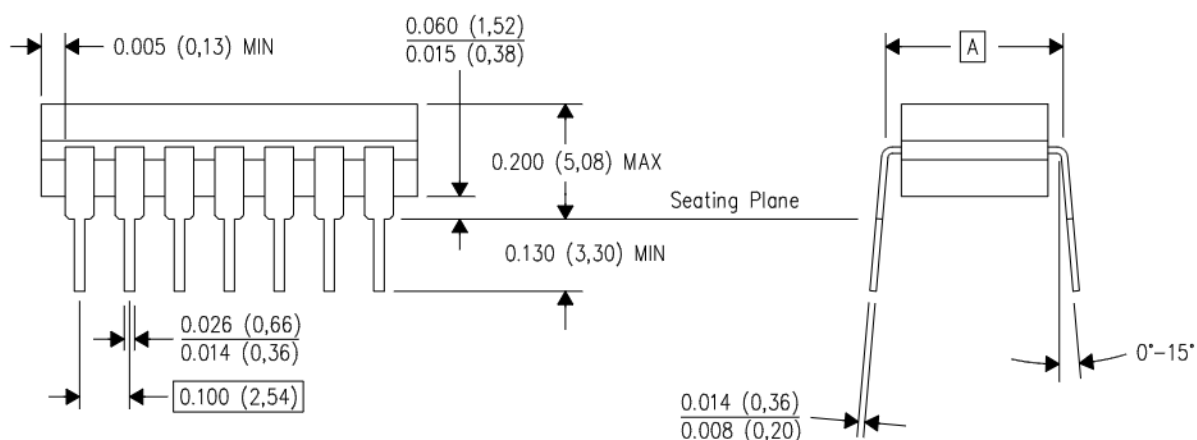
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

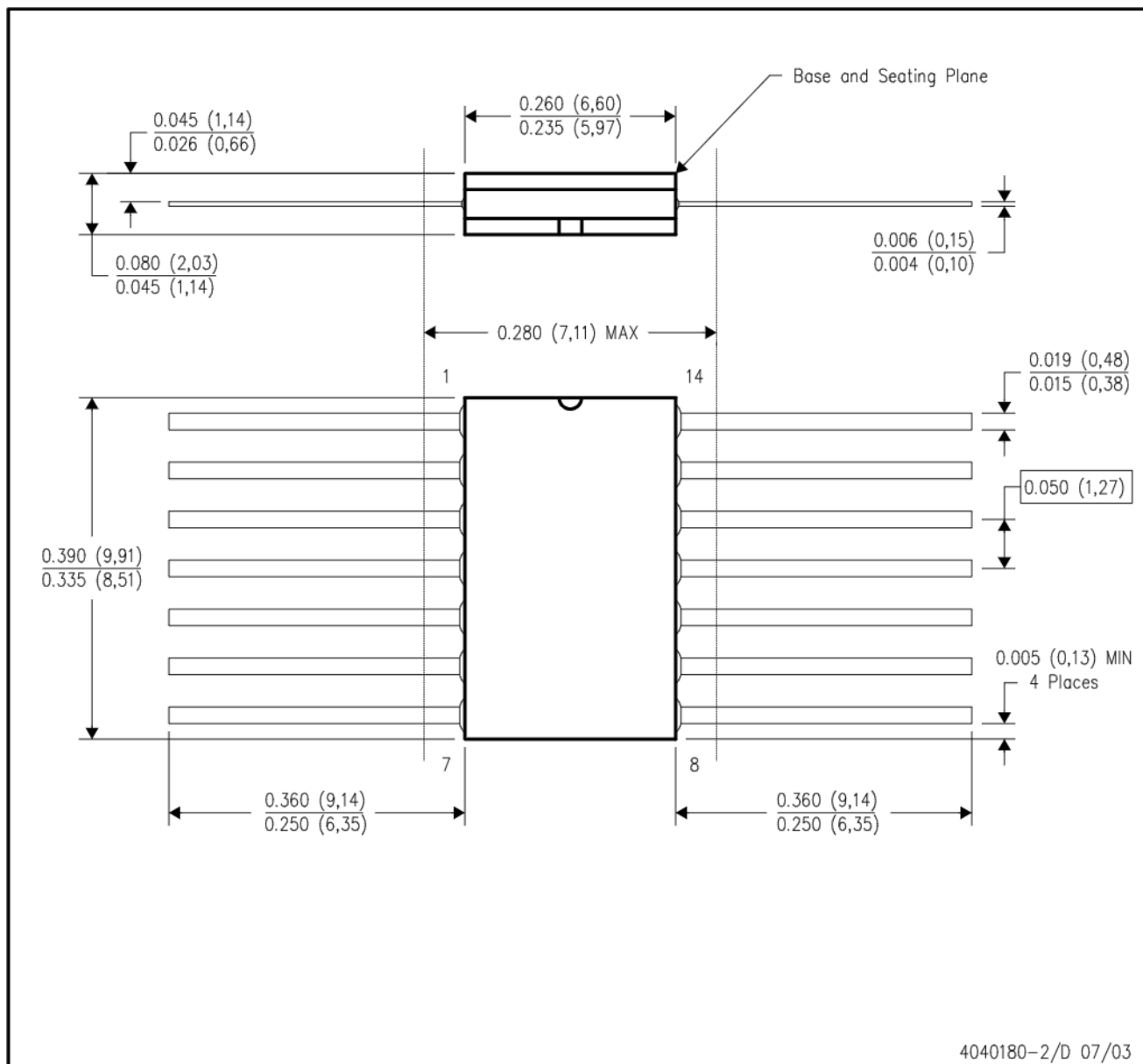


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

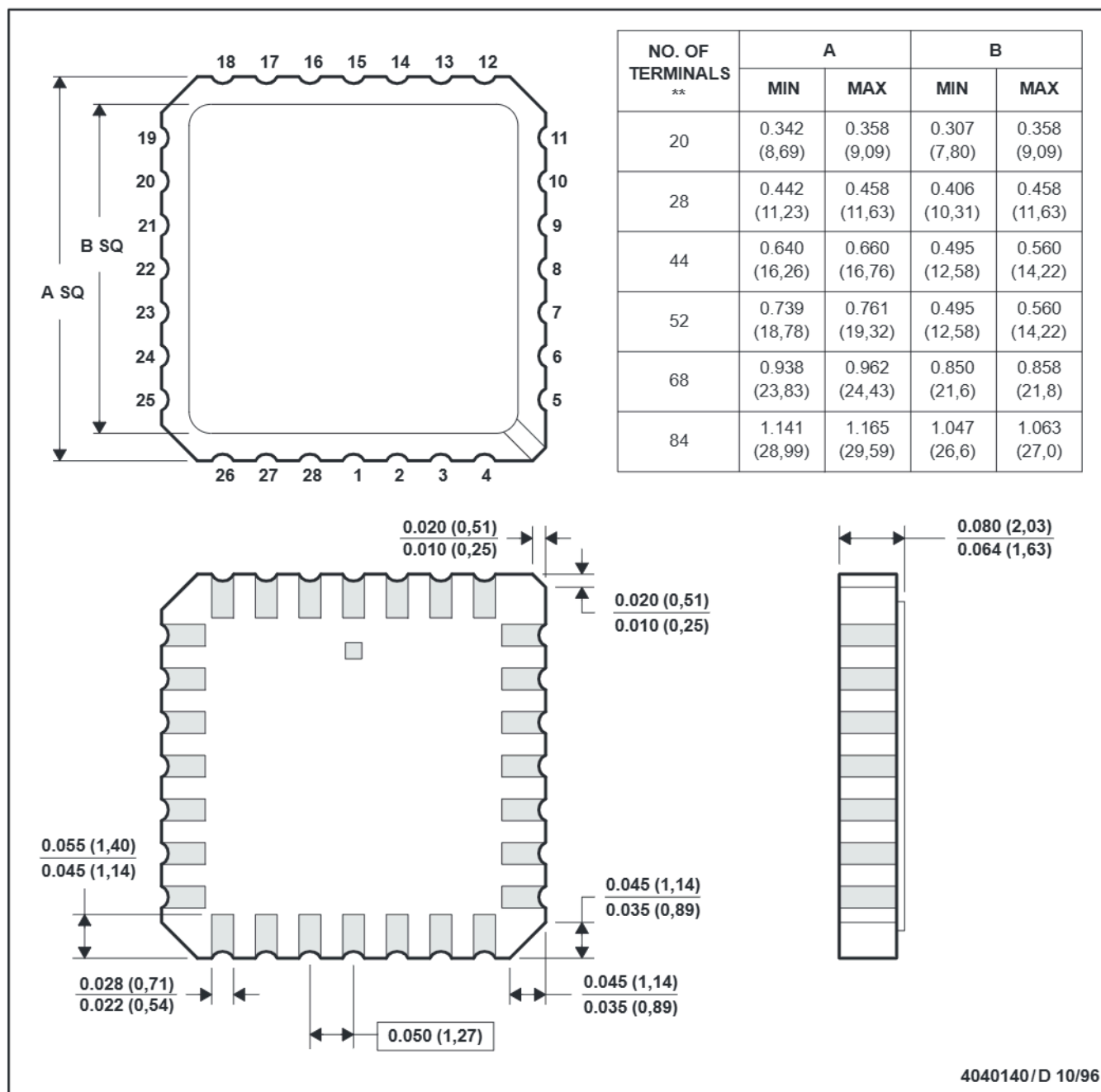


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

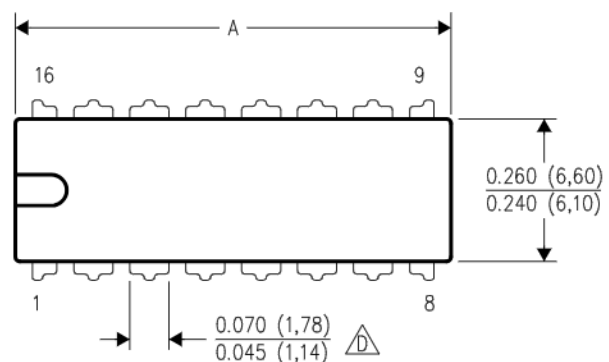


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

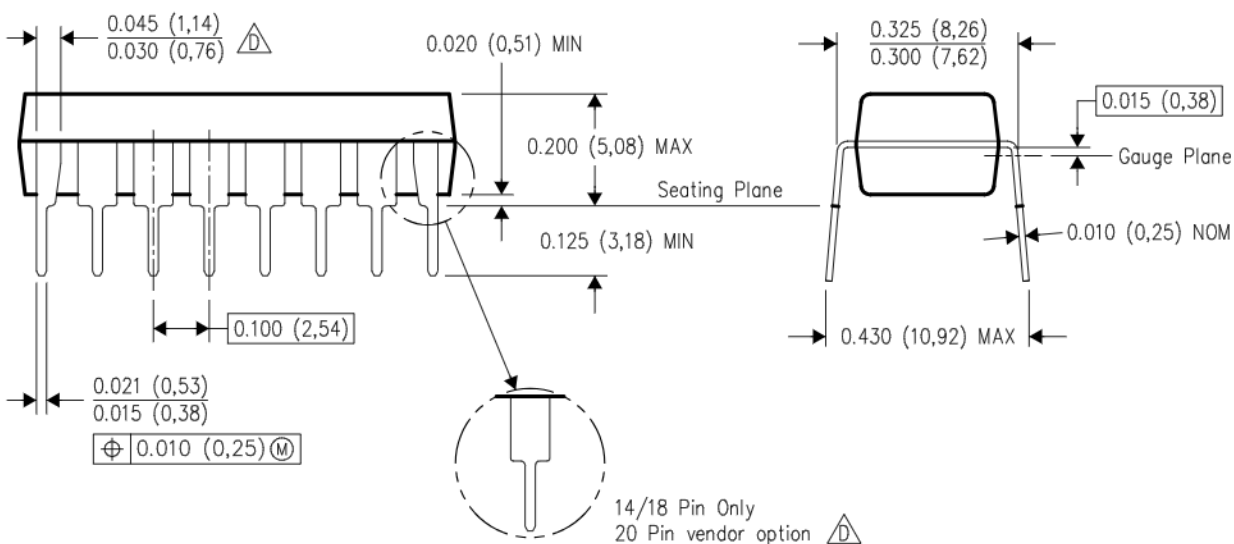
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

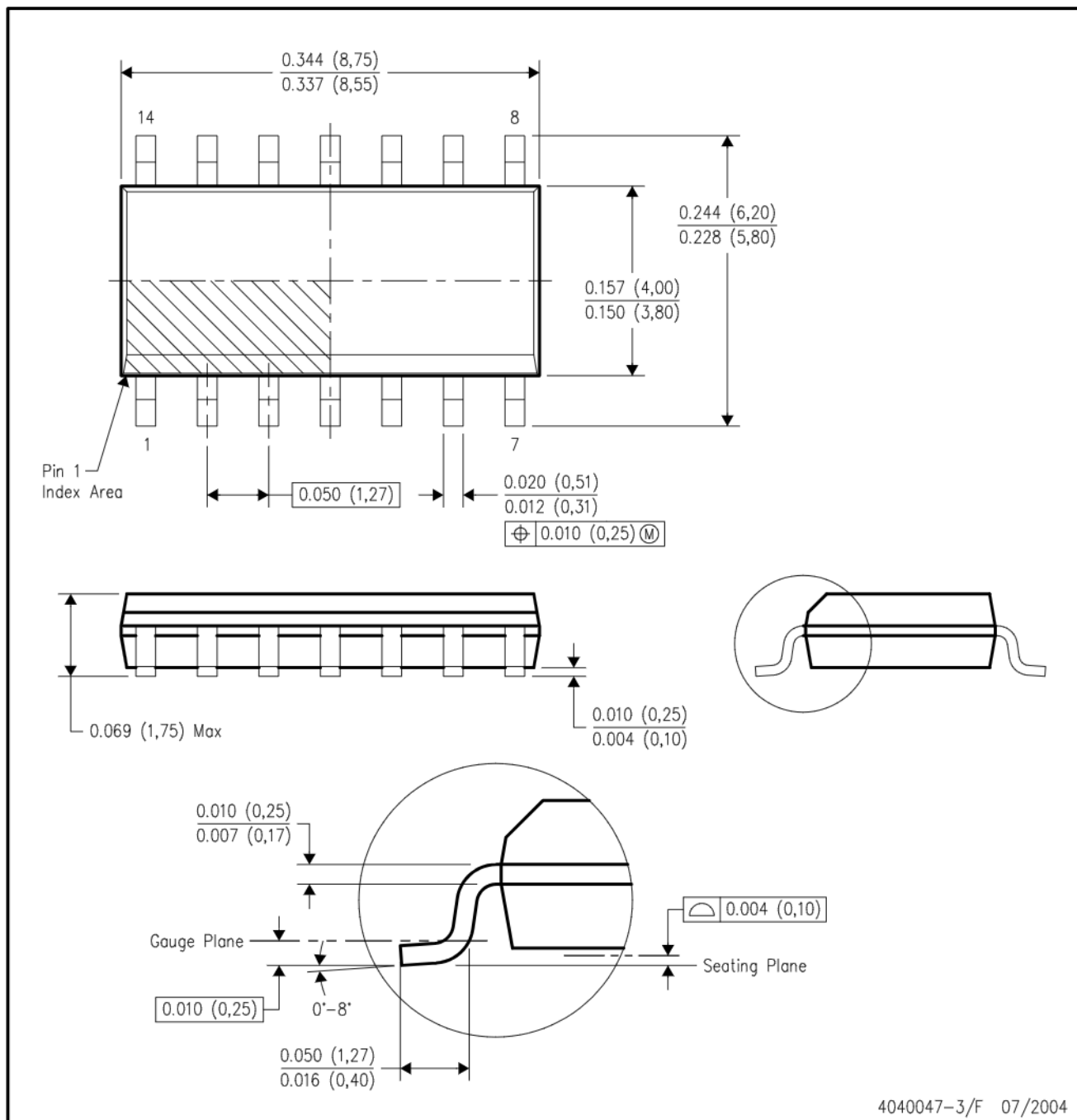


4040049/E 12/2002

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
- △ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- △ The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-012 variation AB.

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